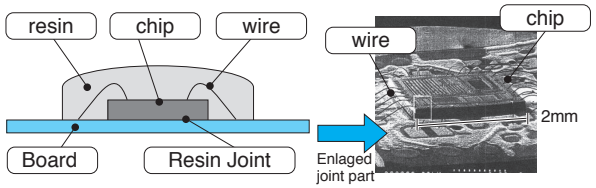
Function Modules Technologies

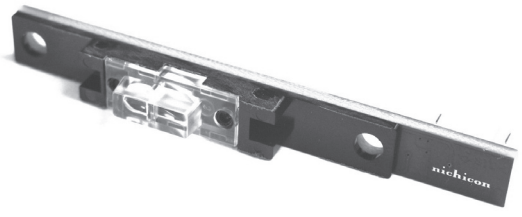
Mount Technology Segment	Purpose and means	Application technology
Mounting Board	High Density Wiring	Multilayer Resin Board
	Functional Board	Ceramic Board
		Dissimilar Material composite Board
		Metal Base Board
High Density Mounting	Extremely-compact Parts	0.6×0.3mm Parts
	Unique Shaped Parts	CSP, BGA
Bare-Chip Mounting	Wire Bonding	Thin Wire
		Thick Wire

Signal Line Type — **Thin Wire Bonding**

- Use Aluminum Wire
- Use Wedge Bonding
- Surface mounting parts mixtured is available

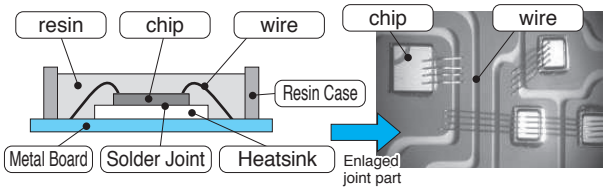


application case : Toner Quantity Sensor



Power Line Type — **Thick Wire Bonding**

- Max. ϕ500μm wire usable
- Pb free solder joint
- High Density Materials compliant for Large electric power (Substrate and Heatsink)



application case : Power Module